

METHOD AND DEVICE OF PEELING SEMICONDUCTOR DEVICE USING
ANNULAR CONTACT MEMBERS

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ABSTRACT OF THE DISCLOSURE

10 In a semiconductor device manufacturing process, a semiconductor wafer is diced into a plurality of semiconductor chips, which are then peeled, from a dicing tape, using a peeling device. The peeling device includes a plurality of annular contact members arranged one after another from the outside to the inside, and the 15 annular contact members are operated so that the semiconductor chip is successively peeled from the tape from the outer circumferential portion thereof toward the central portion thereof.

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